



RESINIFY — INSTRUCTIONS FOR USE (IFU)

HighTemp 150 (RT-HT150) — High-Temperature Engineering Resin For Heat-Resistant Fixtures, Functional Testing & Thermal Applications up to 150°C

1. Product Overview

HighTemp 150 is a heat-resistant engineering resin designed for parts exposed to elevated temperatures, mechanical loading, and thermal cycling. Ideal for functional testing, hot-air or fluid environments, and applications needing low thermal deformation.

2. Printer Compatibility

- LCD / mSLA / DLP printers
- 385–405 nm wavelength
- Optimized for high-stability engineering parts

3. Printing Instructions

Parameter	Recommended
Layer Height	50–100 µm
Normal Exposure	3.2–4.2 sec
Bottom Exposure	45–60 sec
Bottom Layers	6–8
Lift Speed	Medium
Light-Off Delay	Enabled

Support Tips:



- Use heavy supports for heat-resistant parts.
- Angle 20–25° to prevent warping during printing.
- Reinforce long or bulky geometries.

4. Cleaning Instructions

- Wash **2–3 minutes** in IPA or resin cleaner.
- Ensure full drying—trapped IPA lowers heat resistance.
- Avoid ultrasonic cleaning.

5. Post-Curing Instructions

- UV cure **25–35 minutes**.
- **Required heat cure for full HDT:**
 - i. **Stage 1:** 60°C for 20–30 minutes.
 - ii. **Stage 2:** 90–100°C for 20 minutes.
- Controlled cooling is recommended.

6. Usage Guidelines

- Suitable for high-temp fixtures, electronics housings, hot-air ducts.
- Excellent for form-fit testing requiring thermal performance.
- Avoid sudden temperature shocks.
- Not intended for direct flame contact.

7. Safety & Disposal

- Wear gloves, mask, and eye protection.
- Cure all waste resin before disposal.
- Dispose of IPA per environmental guidelines.